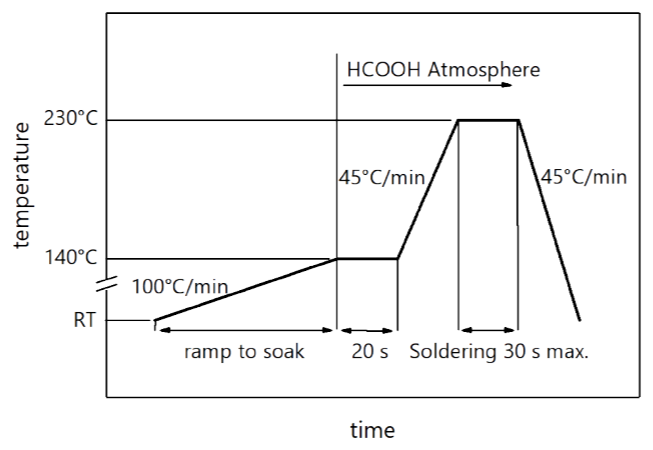
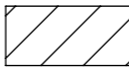
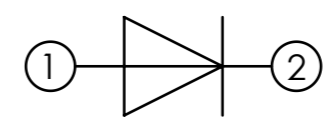


recommended solder condition



 TiW 0.1µm, Cu 45.0µm, Ni 2.0µm, Pd 0.05µm, Au 0.05µm



Material:		nanoplus Nanosystems and Technologies GmbH Oberer Kirschberg 4, 97218 Gerbrunn, Germany		Description:	
Finish:		© copyright nanoplus GmbH 2021, all rights reserved nanoplus GmbH reserves the right to modify specifications at any time without notice and is not liable for errors.		Drawn by: FR	
Unless Otherwise Stated: ± 0,03		Drawing Scale: 20:1		Drawn Date: 05.03.2021	
Surface Finish: All Dimensions: mm		Approx Weight:		Checked/Approved by: OK	
Drawing Scale: 20:1		Drawing Produced In Accordance With: BS8888		Checked/Approved Date: 08.03.2021	
Projection Method: THIRD ANGLE		Sheet Size: A3		Part Name: Chip on ceramics carrier	
Legal Owner: Nanosystems and Technologies GmbH		nanoplus		Drawing Number: 000618	
				Sheet: 1 of 1	
				Revision:	